

# Copper Gleam™ CF-25

## Viafill Bath

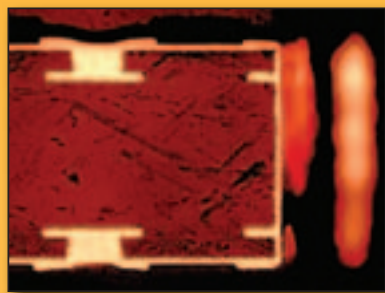
### *Advanced Viafilling Technology*

#### Description

A versatile, simple, easy to operate plating bath that can help you expand your plating capacity without additional capital expenditure. It can fill vias and thru-holes concurrently and is compatible with pattern, panel and button plating.

#### Benefits

- Simultaneous via-filling and through-hole plating
- Exceptional metal distribution
- Simple two-component process
- Easy-to-analyze with conventional CVS procedures
- No dummy plating requirement



Via Diameter: 140  $\mu\text{m}$   
Via Depth: 90  $\mu\text{m}$   
Plating Thickness: 37  $\mu\text{m}$



Via Diameter: 50  $\mu\text{m}$   
Via Depth: 50  $\mu\text{m}$   
Plating Thickness: 32  $\mu\text{m}$

[Click here for more information](#)